

PAM3131

3A ADJUSTABLE LOW VOLTAGE LOW DROPOUT CMOS REGULATOR

Description

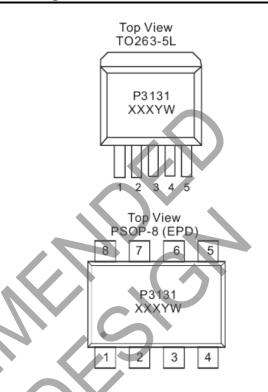
The PAM3131 is a 3A CMOS adjustable LDO regulator that features a low quiescent current, ultra low input, output, and dropout voltages, as well as over temperature protection. It is available in TO-263 and PSOP-8 (Exposed Pad) packages. The output voltage is adjustable from 0.9V to 3.3V. The PAM3131 is stable with a ceramic output capacitor of 1.0μ F or higher.

This family of regulators can provide either a stand alone power supply solution or act as a post regulator for switch mode power supplies. They are particularly well suited for applications requiring low input and output voltages.

Features

- Low-Dropout Regulator Supports Input Voltages Down to 1.4V
- Low Dropout Voltage: 300mV@ 3A
- Output Voltage Adjustable from 0.9V-3.3V
- Stable with a Ceramic Output Capacitor of 1.0µF or Higher
- Low Quiescent Current
- Current Limit
- Over Temperature Shutdown
- Short Circuit Current Protection
- Low Temperature Coefficient
- Standard TO-263 and PSOP-8 (Exposed Pad) Packages
- Pb-Free Package

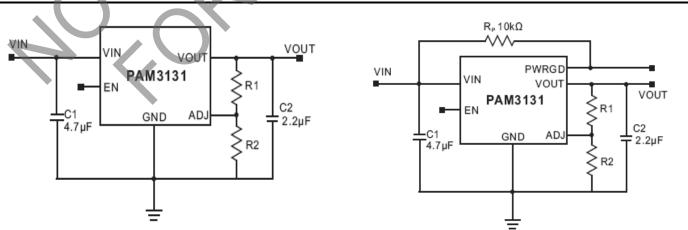
Pin Assignments



Applications

- DSP, FPGA, and Microprocessor Power Supplies
 - 1.2V Core Voltage for DSPs
 - SATA Power Supply
- LCD TV/ Monitors
- Wireless Devices
- Communication Devices
- Portable Electronics
- Post Regulator for SMPS

Typical Applications Circuit

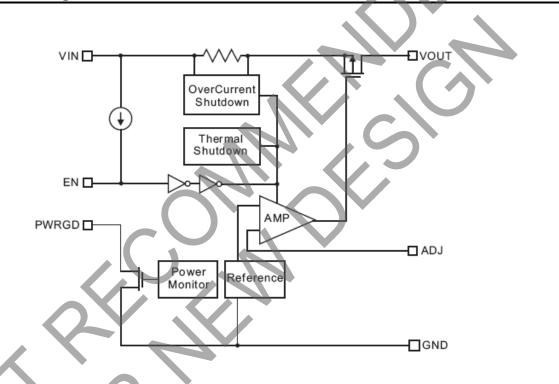




Pin Description

I					
Pin Name	Pin N	umber	Function		
	TO263-5L	PSOP-8(EPD)			
VIN	1	2	Input		
EN	2	3	Enable Pin		
ADJ	4	6	Adjustable Pin		
VOUT	5	7	Output		
GND	3	1, 4, 8	Ground		
PWRGD		5	Power Good		

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for prolonged time periods may affect device reliability. All voltages are with respect to ground.

Parameter	Rating	Unit
Input Voltage	4.0	V
Output Pin Voltage	-0.3 to V _{IN} +0.3	V
Operation Temperature Range	-40 to +85	°C
Operation Junction Range	-40 to +125	°C
Maximum Output Current	$P_D/(V_{IN}-V_O)$	-
Storage Temperature	-65 to +150	°C
Maximum Junction Temperature	150	°C
Soldering Temperature	300, (5sec)	°C



Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Parameter	Rating	Unit	
Supply Voltage Range	1.4 to 3.6	V	
Operation Temperature Range	-40 to +85	- °C	
Junction Temperataure Range	-40 to +125		

Thermal Information

Parameter	Symbol	Package	Max	Unit
Thermal Desistance (Junction to Coop)	Case) θ _{JC}	TO-263	7	
Thermal Resistance (Junction to Case)		PSOP-8	10	
Thermal Desistance (lunction to Ambient)	0	TO-263	35	°C/W
Thermal Resistance (Junction to Ambient)	θ _{JA}	PSOP-8	50	
Internel Device Dissignation (T. 25%C)	D	TO-263	2800	
Internal Power Dissipation ($T_A = 25^{\circ}C$)	PD	PSOP-8	2000	mW

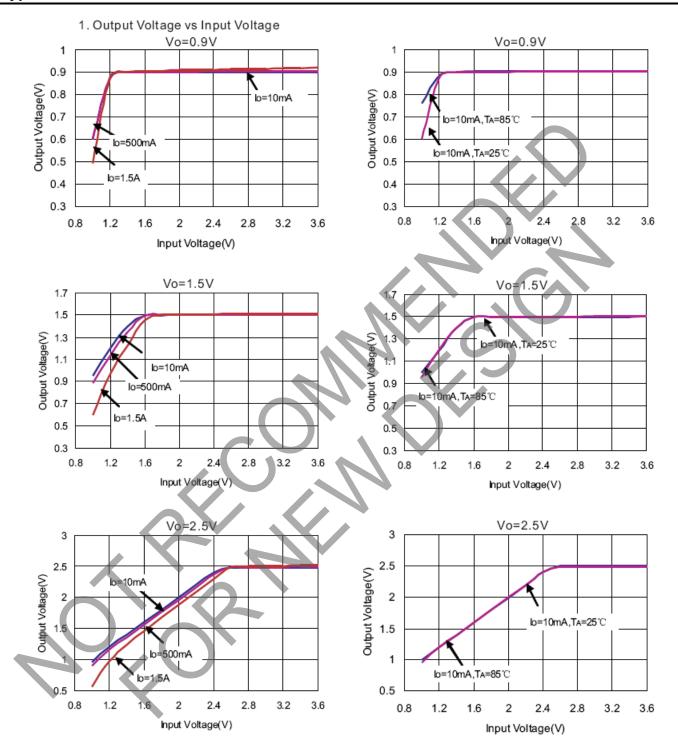


Electrical Characteristics (@T_A = +25°C, $V_{IN} = V_O + 1V$, $C_{IN} = 4.7\mu$ F, $C_O = 4.7\mu$ F, unless otherwise specified.)

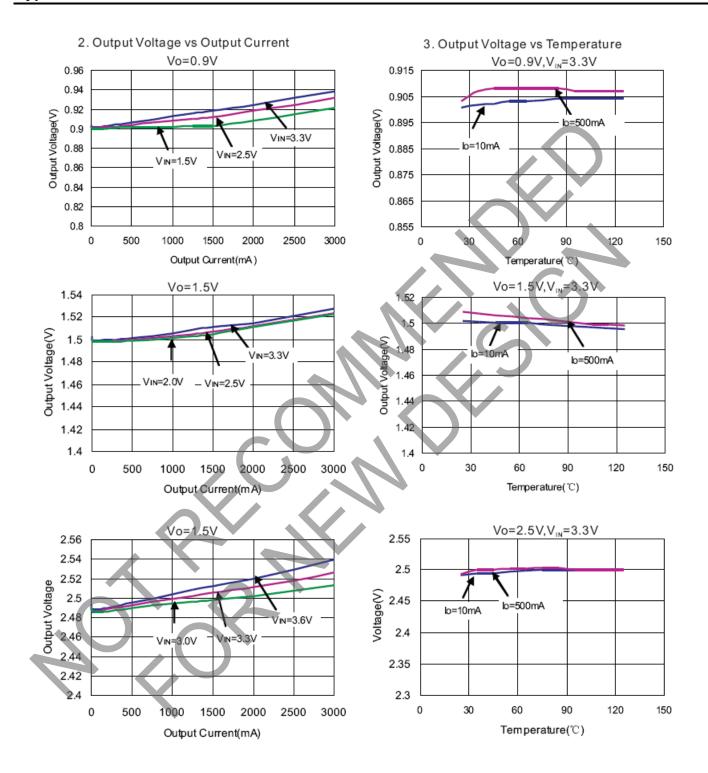
Parameter	Symbol	Test Conditions		Min	Тур	Max	Units
Input Voltage Range	V _{IN}			Note 1		3.6	V
ADJ Reference Voltage	V _{REF}	I _O = 100mA		0.882	0.900	0.918	V
			$V_{\rm O} = 0.9 V$		330	500	mV
		I _O = 500mA	V _O = 1.0V		220	400	
			2.5V > V _O ≥ 1.2V		50	200	
Dren out Malta re			V _O ≥ 2.5V		40	150	
Dropout Voltage	Vdrop		V _O = 0.9V		500		
			V _O = 1.0V		400		
		I _O = 3.0A	2.5V > V _O ≥ 1.2V		350		
			V ₀ ≥ 2.5V		300		
Short Circuit Current	I _{SC}	V _O < 0.3V			1.0		Α
Output Current	Ι _Ο			3.0		Note 2	Α
Quiescent Current	Ι _Q	$I_{O} = 0 m A$			90	150	μA
Ground Pin Current	I _{GND}	V _O > 0.8V				1.0	mA
Line Regulation	LNR	$ \begin{array}{c} V_{O} \leq 2.5V, \ I_{O} = 10mA \\ \hline V_{IN} = V_{O} + 0.5V \ to \ V_{O} + 1.5V \\ \hline V_{O} > 2.5V, \ I_{O} = 10mA \\ \hline V_{IN} = 3.3V \ to \ 3.6V \end{array} $		0.2	1.0	%/V	
Load Regulation	LDR	$I_0 = 1$ mA to 3.0A, $V_{IN} = V_0 + 0.5$ A			0.5	2	%/A
Over Temperature Shutdown	OTS				150		°C
Over Temperature Hysteresis	OTH				50		°C
Temperature Coefficient	Tc				40		ppm/°C
Power Supply Ripple Rejection	PSRR	I _O = 100mA, V _O = 1.5\	/ f = 100Hz f = 1kHz		64 58		dB
Output Noise	Vn	f = 10Hz to 100kHz			40		μV _{RMS}

Notes: 1. The minimum input voltage () of the PAM3131 is determined by output voltage and dropout voltage. The minimum input voltage is defined as: 2. Output current is limited by P_D, maximum I₀ = P_D/(V_{IN(MAX)} -V₀).

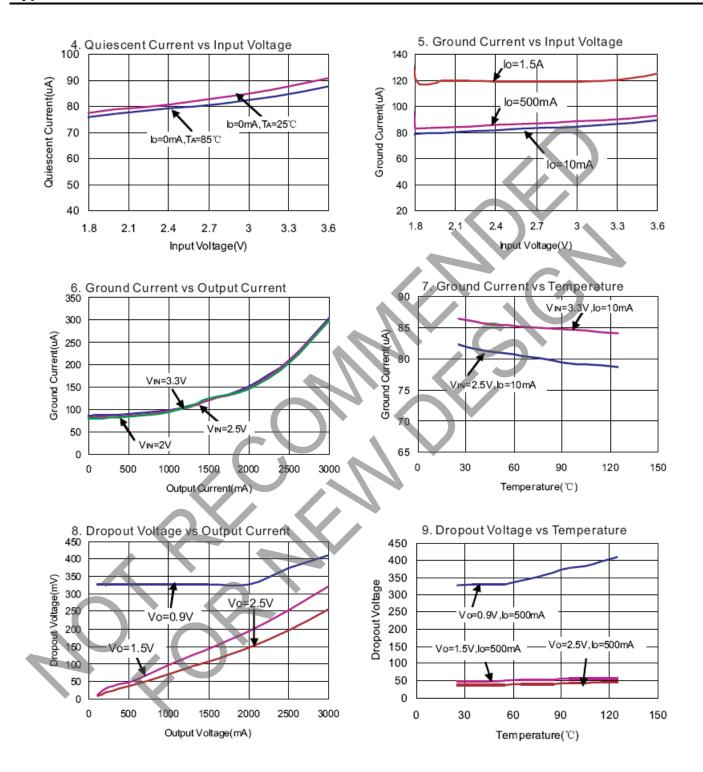




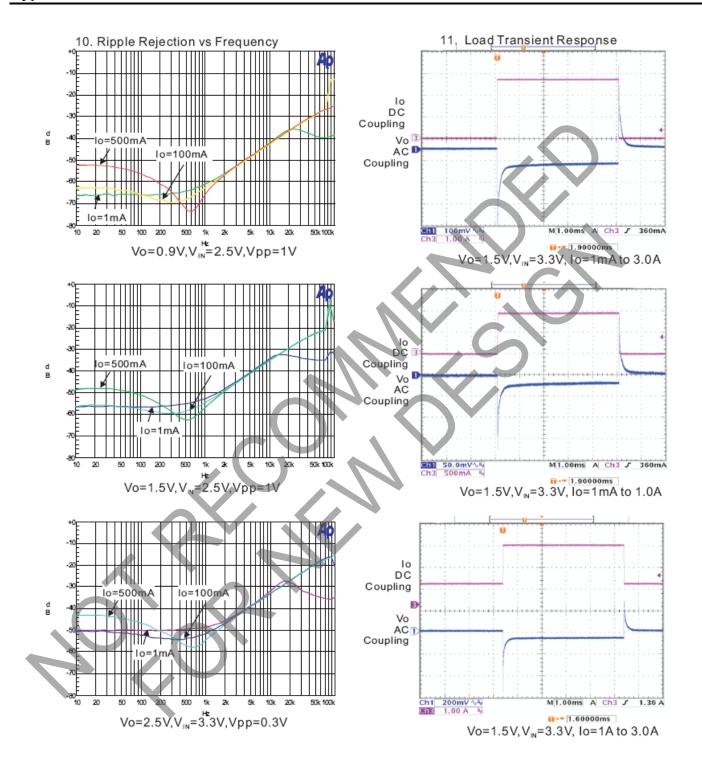




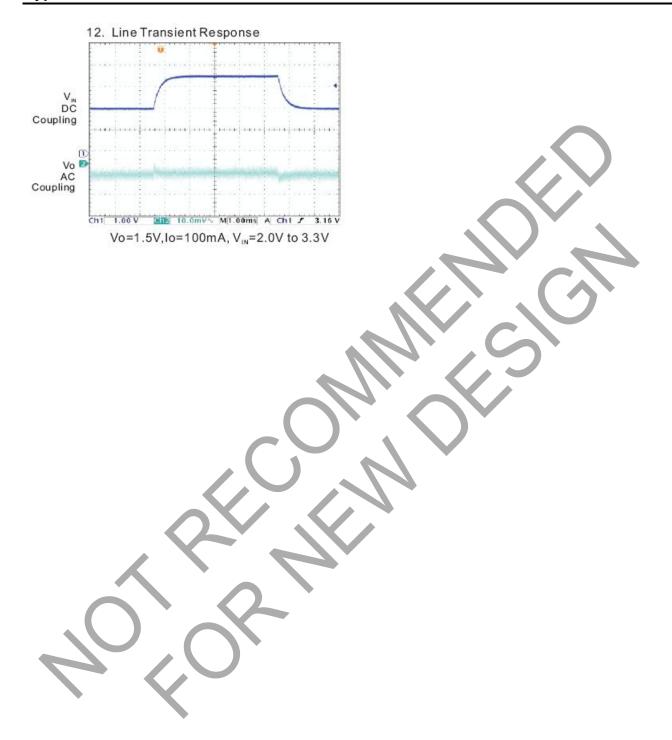














Application Information

The PAM3116 family of low-dropout (LDO) regulators have several features that allow them to apply to a wide range of applications. The family operates with very low input voltage and low dropout voltage (typically 300mV at full load), making it an efficient stand-alone power supply or post regulator for battery or switch mode power supplies. The 1.5A output current make the PAM3116 family suitable for powering many microprocessors and FPGA suppl ies. The PAM3116 family also has low output noise (typically 50µVRMS with 4.7µF output capacitor), making it ideal for use in telecom equipment.

External Capacitor Requirements

A 4.7μ F or larger ceramic input bypass capacitor, connected between V_{IN} and GND and located close to the PAM3116, is required for stability. A 4.7μ F minimum value capacitor from V₀ to GND is also required. To improve transient response, noise rejection, and ripple rejection, an additional 1 0 μ F or larger, low ESR capacitor is recommended at the output. A higher-value, low ESR output capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source, especially if the minimum input voltage of 2.5V is used.

Regulator Protection

The PAM3116 features internal current limiting, thermal protection and short circuit protection. During normal operation, the PAM3116 limits output current to about 2.5A. When current limiting engages, the output voltage scales back linearly until the over current condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds +150°C, thermal-protection circuitry will shut down. Once the device has cooled down to approximately +40°C below the high temp trip point, regulator operation resumes. The short circuit current of the PAM3116 is about 0.7A when its output pin is shorted to ground.

Thermal Information

The amount of heat that an LDO linear regulator generates is:

$$P_{D} = (V_{IN} - V_{O})I_{C}$$

All integrated circuits have a maximum allowable junction temperature $(T_{J(MAX)})$ above which normal operation is not assured. A system designer must design the operating environment so that the operating junction temperature (T_J) does not exceed the maximum junction temperature $(T_{J(MAX)})$. The two main environmental variables that a designer can use to improve thermal performance are air flow and external heat sinks. The purpose of this information is to aid the designer in determining the proper operating environment for a linear regulator that is operating at a specific power level.

In general, the maximum expected power ($P_{D(MAX)}$) consumed by a linear regulator is computed as:

Where:

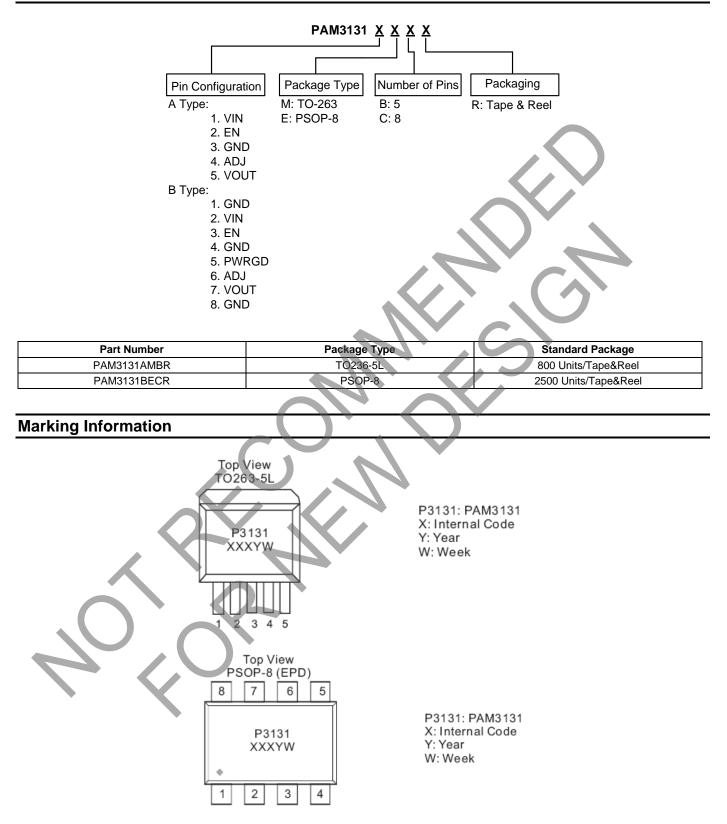
- V_{I(AVG)} is the average input voltage.
- V_{O(AVG)} is the average output voltage.
- I_{O(AVG)} is the average output current.
- I_(Q) is the quiescent current.

For most LDO regulators, the quiescent current is insignificant compared to the average output current; therefore, the term $V_{I(AVG)}$ xl_Q can be neglected. The operating junction temperature is computed by adding the ambient temperature (T_A) and the increase in temperature due to the regulator's power dissipation. The temperature rise is computed by multiplying the maximum expected power dissipation by the sum of the thermal resistances between the junction and the case R_{BJC}), the case to heatsink (R_{BCS}), and the heatsink to ambient (R_{BSA}). Thermal resistances are measures of how effectively an object dissipates heat. Typically, the larger the device, the more surface area available for power dissipation so that the object's thermal resistance will be lowers.



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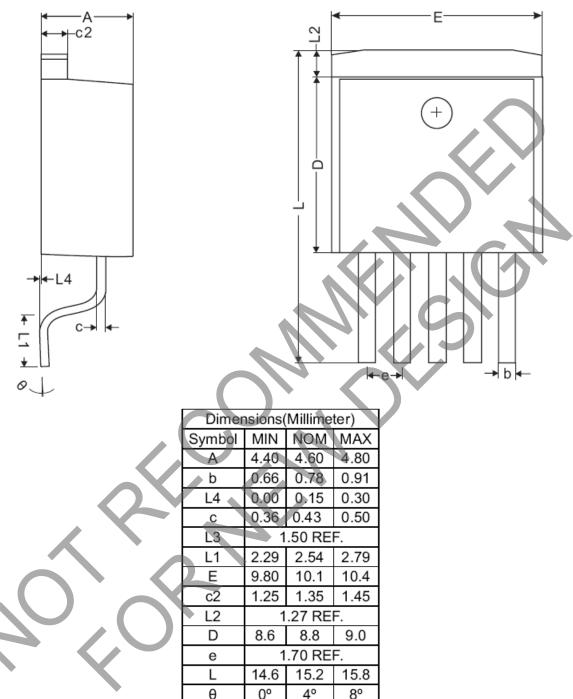
Ordering Information





Package Outline Dimensions (All dimensions in mm.)



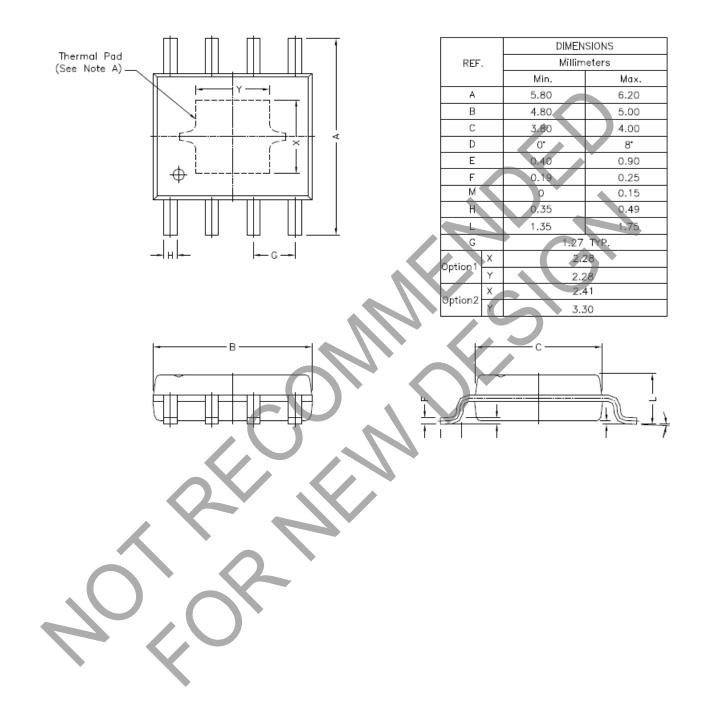




PAM3131

Package Outline Dimensions (cont.) (All dimensions in mm.)

PSOP-8







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